

THE SELECTIVE CHEMICAL-MECHANICAL POLISHING PROPERTIES OF A  
CROSS-LINKED POLYMER AND SPECIFIC APPLICATIONS THEREFOR

ABSTRACT OF THE DISCLOSURE

The present invention is directed, in general, to a method of polishing a surface on substrates, such as semiconductor wafers and, more specifically, to a polishing pad suitable for this purpose. The polishing pad comprises a polishing body that includes a cross-linked polymer material, and may be incorporated into a polishing apparatus. Polishing includes positioning the substrate containing at least one layer against the polishing body and polishing the layer.